

In the claims:

1. (Once Amended) An apparatus, comprising:

a plurality of bond pads configured in an array;

B² a first plurality of driver cells located nearer to a nearest die edge than the plurality of bond pads; and

a second plurality of driver cells located farther from the nearest die edge than the plurality of bond pads.

3. (Once Amended) The apparatus of claim 2, further comprising a plurality of

B³ pre-drive cells located farther from the nearest die edge than the second plurality of driver cells.

9. (Once Amended) A semiconductor device, comprising:

a die including

B⁴ a plurality of bond pads configured in an array,

a first plurality of driver cells located nearest to a nearest die edge than the plurality of bond pads, and

a second plurality of driver cells located farther from the nearest die edge than the plurality of bond pads; and

a lead frame coupled the plurality of bond pads by a plurality of bond wires.

11. (Once Amended) The semiconductor device of claim 10, further comprising

B⁵ a plurality of pre-drive cells located farther from the nearest die edge than the second plurality of driver cells.